

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







FC4T Series

Metal Foil Low Value Chip

The FC4T chip features four terminals, also known as a "Kelvin" configuration. This configuration enables current to be applied through two opposite terminals and a sensing voltage to be measured across the other two terminals, eliminating the resistance and temperature coefficient of the terminals for a more accurate current measurement. Ohmite's proprietary Metal Foil technology offers an excellent Temperature Coefficient of Resistance (TCR) even for very low resistance values (down to 50ppm).



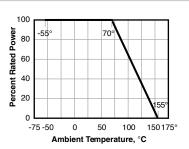
SERIES SPECIFICATIONS

		Power	Resistance		
	Pkg.	Rating	Range	TCR	
Series	Size	(W @70°C)	(Ω)	(ppm/°C)	Tolerance
FC4T	1206	0.5W	0.005-0.100	50ppm	0.5%, 1%

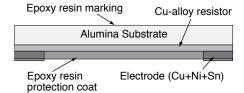
CHARACTERISTICS

Resistance	0.005-0.100
Operating Temp. Range	-55°C to +155°C
Rated Power	0.5 watt
Resistance Tolerance	0.5% and 1% standard
Temperature Coefficient	within ± 50 ppm, ± 100 ppm for 5 m Ω
Coating Material	Epoxy resin
Terminals	Cu/Ni/Sn
Max. Current	√(Max. power÷ Resistance value)
Res. of Electrodes	<5mΩ

Derating



Construction



Peeling Strength of Seal Tape

F = Peel-back force: 0.1 - 0.7N (10 - 71gf)



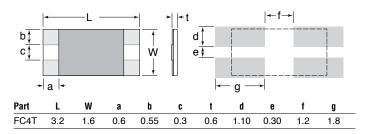
FC4T Series

Metal Foil Low Value Chip

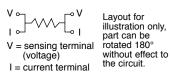
PERFORMANCE CHARACTERISTICS					
Test Items	Performance	Test Methods			
Short time overload	±(1.0%+0.5mΩ)	P= 2.5Pr; T=25 ±2°C, t=5sec.; IEC60115-1 4.13			
High Temp. Exposure	±(1.0%+0.5mΩ)	T=+170 ±2°C; t=1000h; IEC60115-1 4.25			
Low Temp. Storage	±(1.0%+0.5mΩ)	T=-55 ±2°C; t=1000h; IEC60115-1 4.25			
Moisture Load Life	±(2.0%+0.5mΩ)	Vtest=Vmax; T=60 ±2°C; RH=95%; t= 90min ON, 30min OFF, 1000h; IEC60115-1 4.25 (60°C, 95%RH)			
Thermal Shock	±(1.0%+0.5mΩ)	-55°C 30min. / R.T. 3min. / +150°C 30min. / R.T. 3min], 100cycles; IEC60115-1 4.19			
Load Life at 70°C	±(2%+0.5mΩ)	Vtest=Vmax; T=70 ±2°C; t=90min ON; IEC60115-1 4.25			
Solderability	The covered area >95%	Dip into solder at T=245 ±5°C, t=3 ±0.5sec.; IEC60115-1 4.17			
Resistance to Solder Heat	±(1.0%+0.5mΩ)	Through Reflow T=275 ±5°C, t=20 ±1sec.; IEC60115-1 4.18			
Mechanical Shock	±(1.0%+0.5mΩ)	a=100G, t=11ms, 5 times shock; IEC60115-1 4.21			
Substrate Bending	±(1.0%+0.5mΩ)	Span between fulcrums 90mm; bend width 2mm; test board glass-epoxy; Thickness=1.6mm; IEC60115-1 4.33			

DIMENSIONS

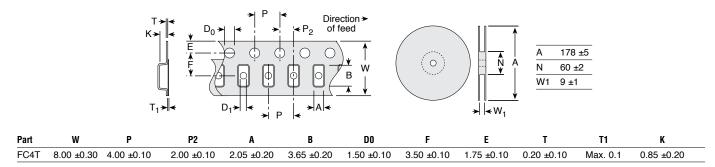
(mm ±0.2)



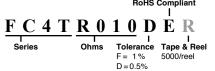
Schematic



Tape and Reel



ORDERING INFORMATION



Standard Part Numbers

1%	0.5%
FC4TR005FER FC4TR010FER FC4TR015FER FC4TR050FER FC4TR100FER	FC4TR010DER FC4TR015DER FC4TR050DER FC4TR100DER

